

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously Presented) A semiconductor device comprising:
a supporting substrate made of insulating material;
a conductive pattern provided on a surface of the supporting substrate;
an external connecting terminal provided on a back surface of the supporting substrate
and electrically connected to the conductive pattern through the substrate;
a circuit element provided on the conductive pattern;
a glass plate that covers the circuit element and that forms a hollow airtight portion
between the supporting substrate and the glass plate; and
a light-shielding adhesive resin applied over an entire surface of the glass plate.

2. (Canceled)

3. (Original) A semiconductor device according to claim 1, wherein the circuit element
includes a semiconductor element or a fuse element.

4. (Withdrawn) A semiconductor device manufacturing method comprising steps of:
preparing a supporting substrate in which a conductive pattern having a large number of
mounting portions on a surface of the supporting substrate is provided and external connecting
terminals are provided on a back surface;
fixing the circuit element onto the mounting portions respectively;

applying an adhesive resin to an overall adhesive surface of a glass plate that covers the circuit element and forms an airtight hollow portion between the supporting substrate and the glass plate every mounting portion;

adhering the supporting substrate and the glass plate to form the airtight hollow portion every mounting portion; and

dividing the supporting substrate into respective mounting portions by dicing adhered portions between the supporting substrate and the glass plate.

5. (Withdrawn) A semiconductor device manufacturing method according to claim 4, wherein the adhesive resin is formed of a light-shielding adhesive resin.

6. (Withdrawn) A semiconductor device manufacturing method comprising steps of:
preparing a supporting substrate in which conductive patterns having a number of mounting portions thereon are provided on a surface of the supporting substrate and external connecting terminals are provided on a back surface of the supporting substrate;

fixing a circuit element onto respective mounting portions;

mounting a lattice-like column member on the supporting substrate;

applying an adhesive resin to an overall adhesive surface of a glass plate that covers the circuit element and forms an airtight hollow portion between the supporting substrate and the glass plate every mounting portion;

adhering a glass plate onto the column member to cover the circuit element and to form a hollow airtight portion formed by the supporting substrate, the column member and the glass plate every mounting portion; and

dividing the supporting substrate into respective mounting portions by dicing adhered portions between the supporting substrate and the glass plate.

7. (Withdrawn) A semiconductor device manufacturing method according to claim 6, wherein the adhesive resin is formed of a light-shielding adhesive resin.

8. (Previously Presented) A semiconductor device comprising:
a substrate;
a circuit member provided on the substrate;
a terminal provided on a back of the substrate and electrically connected to the circuit member through the substrate;
a wall surrounding the circuit member; and
a transparent plate with a light-shielding adhesive resin provided over the transparent plate's entire surface, said transparent plate adhered on the wall and over the circuit member to form an airtight cavity between the substrate and the transparent plate.

9. (Previously Presented) The semiconductor device according to claim 8 wherein the circuit member comprises:

- a conductive pattern disposed over the substrate; and
- a semiconductor chip disposed over the conductive pattern.

10. (Previously Presented) The semiconductor device according to claim 8 wherein the substrate comprises insulating material.

11. (Previously Presented) The semiconductor device according to claim 8, wherein the circuit member includes a fuse element.

12. (Previously Presented) The semiconductor device according to claim 1, wherein said external connecting terminal is electrically connected to the conductive pattern through the substrate by a via hole.

13. (Previously Presented) The semiconductor device according to claim 8, wherein said terminal is electrically connected to the conductive pattern through the substrate by a via hole.

14. (New) The semiconductor device according to claim 12, wherein said via hole extends substantially straight between an internal surface and an external surface of the substrate.

15. (New) The semiconductor device according to claim 13, wherein said via hole extends substantially straight between an internal surface and an external surface of the substrate.